Takatori

MODEL

TEAM-200

Automatic Backgrind Tape Removal for Post-Mount Processes

Outline

The ideal system for removing B/G tape from the wafer mounted to dicing frames, following the backgrind process.

Features

- Wafer alignment based on wafer circumference ensures accurate positioning from manual mounter.
- Compatible with thin wafer applications.
- Using a specially designed wafer handler, the tape is removed in a stress-free process (wafers > 50 micron).
- One-touch operation for switching removal orientation.
- Specialized backgrind tape removal mechanism.
- Option: UV unit

In line system for pairing with ATM-8100S

For 50 μ wafers

Patent Pending

Specification		TEAM-200
Throughput		60 wafers/hour （Depend on data setting）
Wafer Size		6 inch、 8 inch
Tape Width		50mm
Utilities	Power	AC100V Single phase 50／60Hz 1.5 KVA
	Air	Pressure 0.5Mpa 150Nl/min
	Vacuum sourse	—74Kpa
Dimensions		D 900 × W 1,300 × H 1,650 mm
Weight		500 kg

System appearance and specifications are subject to change without prior notice from the supplier.

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